PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT5584942

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
SEQUENCE:	2

CONVEYING PARTY DATA

Name	Execution Date
SUNEDISON SEMICONDUCTOR LIMITED	06/06/2018
MEMC JAPAN LTD	06/06/2018
MEMC ELECTRONIC MATERIALS S.P.A	06/06/2018

RECEIVING PARTY DATA

Name:	GLOBALWAFERS CO., LTD.
Street Address:	NO. 8. INDUSTRIAL EAST ROAD
Internal Address:	SCIENCE-BASED INDUSTRIAL PARK
City:	HSINCHU
State/Country:	TAIWAN
Postal Code:	R.O.C.

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	15995853

CORRESPONDENCE DATA

Fax Number: (314)612-2307

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 3146215070
Email: uspatents@armstrongteasdale.com
Correspondent Name: RICHARD A. SCHUTH
Address Line 1: ARMSTRONG TEASDALE LLP
Address Line 2: 7700 FORSYTH BLVD., SUITE 1800
Address Line 4: ST. LOUIS, MISSOURI 63105

ATTORNEY DOCKET NUMBER:	28744-4848 (150037A.2)
NAME OF SUBMITTER:	RICHARD A. SCHUTH
SIGNATURE:	/Richard A. Schuth/
DATE SIGNED:	06/21/2019
Total Attachments: 7	

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ASSIGNMENT

This Assignment is made by and among SunEdison Semiconductor Limited, a company organized and existing under the laws of Singapore ("**SSL**"), MEMC Japan Limited, a company organized and existing under the laws of Japan ("**MEMC Japan**"), and MEMC Electronic Materials, S.P.A., a company organized and existing under the laws of Italy ("**MEMC EM**", and collectively with SSL and MEMC Japan, the "**Assignors**"), and GlobalWafers Co., Ltd., a company organized and existing under the laws of Taiwan and having its registered address at No. 8. Industrial East Road, Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C. (hereinafter referred to as "**Assignee**");

WHEREAS, on December 31, 2016, Assignors entered into certain IP Transfer Agreements with Assignee;

WHEREAS, the parties hereto desire to memorialize, *nunc pro tunc*, the assignment and ownership of all Assigned IP (defined below) for, among other things, recordal purposes with certain patent administration bodies, such as the United States Patent and Trademark Office; and

WHEREAS, Assignors acknowledge that payment in full from Assignee for all Assigned IP has heretofore been paid.

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, Assignors have agreed to and do hereby sell, assign and transfer, and confirm the sale, assignment and transfer, unto Assignee all of their rights, title and interest throughout the world, including without limitation, the right to sue and recover for any past infringements, in and to the Listed IP, any other applications (including provisional, non-provisional, divisional, continuing, or reissue applications) based in whole or in part on any Listed IP, any corresponding patent or patent applications filed in any country based in whole or in part on, and/or claiming priority from, any Listed IP, any patents (including extensions thereof) of any country based in whole or in part on, and/or claiming priority from, any Listed IP, and all of the inventions described in the Listed IP and all of the aforementioned patents and patent applications (all of the foregoing, collectively, the "**Assigned IP**");

TO BE HELD AND ENJOYED by said Assignee, its successors and assigns, as fully and entirely as the Assigned IP would have been held and enjoyed by Assignors had no assignment of said interest been made.

EACH ASSIGNOR hereby agrees that it will do, execute and deliver, or will cause to be done, executed and delivered, all such further lawful acts, transfers, assignments and conveyances, powers of attorney and assurances for the better assuring, conveying and confirming unto Assignee, all of such Assignor's rights, title and interest in and to the Assigned IP hereby transferred, assigned and conveyed, as Assignee may reasonably require.

[*Signature Pages Follow*]

IN WITNESS WHEREOF, the undersigned have caused these presents to be executed by their respective officers thereunto duly authorized this 6 day of June, 2018.

Assignor:

SUNEDISON SEMICONDUCTOR LIMITED

By: ____________________

Name: Paul Markowitz

Title: Director of Intellectual Property

STATE OF Missouri)

COUNTY OF St. Charles)

On this 6 day of June, 2018, before me, a Notary Public, personally appeared Paul Markowitz, an officer of SUNEDISON SEMICONDUCTOR LIMITED, known to me to be the person who executed the within Assignment, and who did state that said instrument was signed on behalf of said company, and acknowledged to me that he executed the same for the purposes therein stated.

IN TESTIMONY WHEREOF, I have hereunto set my hand and seal the date and year last above written.

Erika Damiani

Notary Public

My Commission Expires:

July 20, 2018

ERIKA DAMIANI
My Commission Expires July 20, 2018
Commission # 14917341

Assignor:

MEMC JAPAN LTD

By: ______________________

Name: Paul Markowitz

Title: Director of Intellectual Property

STATE OF Missouri)

COUNTY OF St. Charles

On this 6 day of June, 2018, before me, a Notary Public, personally appeared Paul Markowitz, an officer of MEMC JAPAN LTD, known to me to be the person who executed the within Assignment, and who did state that said instrument was signed on behalf of said company, and acknowledged to me that he executed the same for the purposes therein stated.

IN TESTIMONY WHEREOF, I have hereunto set my hand and seal the date and year last above written.

Erika Damiani

Notary Public

My Commission Expires:

July 20, 2018

ERIKA DAMIANI

My Commission Expires July 20, 2018

Commission # 14917341

Assignor:

MEMC ELECTRONIC MATERIALS S.P.A.

By: ________________________

Name: Paul Markowitz

Title: Director of Intellectual Property

STATE OF Missouri)

COUNTY OF St. Charles)

On this 6 day of June, 2018, before me, a Notary Public, personally appeared Paul Markowitz, an officer of MEMC ELECTRONIC MATERIALS S.P.A., known to me to be the person who executed the within Assignment, and who did state that said instrument was signed on behalf of said company, and acknowledged to me that he executed the same for the purposes therein stated.

IN TESTIMONY WHEREOF, I have hereunto set my hand and seal the date and year last above written.

Erika Damiani

Notary Public

My Commission Expires:

July 20, 2018

ERIKA DAMIANI
Notary Public - Notary Seal
STATE OF MISSOURI
Commissioned for St. Charles County
My Commission Expires July 20, 2018
Commission # 14917341

For and on behalf of GlobalWafers Co., Ltd.

Assignee:

GLOBALWAFERS CO., LTD.

By: ____________________

Name: Paul Markowitz

Title: Director of Intellectual Property

STATE OF Missouri)

COUNTY OF St. Charles)

On this 6 day of June, 2018, before me, a Notary Public, personally appeared Paul Markowitz, an officer of GLOBALWAFERS CO., LTD., known to me to be the person who executed the within Assignment, and who did state that said instrument was signed on behalf of said company, and acknowledged to me that he executed the same for the purposes therein stated.

IN TESTIMONY WHEREOF, I have hereunto set my hand and seal the date and year last above written.

Erika Damiani

Notary Public

My Commission Expires:

July 20, 2018

ERIKA DAMIANI
Notary Public - Notary Seal
STATE OF MISSOURI
Commissioned for St. Charles County
My Commission Expires July 20, 2018
Commission # 14917341

SCHEDULE A

TITLE	Country	Application Number	Filing Date	Publication Number	Publication Date	Patent Number	Issue Date
CVD APPARATUS	JP	2018-516838	30-Mar-2018				
SEMICONDUCTOR WAFER SUPPORT RING FOR HEAT TREATMENT	US	15/293696	14-Oct-2016	2017-0115063	27-Apr-2017		
METHODS FOR PROCESSING SEMICONDUCTOR WAFERS HAVING A POLYCRYSTALLINE FINISH	TW	105116794	27-May-2016	201705254	1-Feb-2017		
METHODS FOR PROCESSING SEMICONDUCTOR WAFERS HAVING A POLYCRYSTALLINE FINISH	US	15/577515	28-Nov-2017				
METHODS FOR PROCESSING SEMICONDUCTOR WAFERS HAVING A POLYCRYSTALLINE FINISH	CN	201680030931.3	28-Nov-2017	107851579	27-Mar-2018		
METHODS FOR PROCESSING SEMICONDUCTOR WAFERS HAVING A POLYCRYSTALLINE FINISH	EP	16727609.6	19-Dec-2017	3304580	11-Apr-2018		
METHODS FOR PROCESSING SEMICONDUCTOR WAFERS HAVING A POLYCRYSTALLINE FINISH	JP	2017-559654	15-Nov-2017				
SYSTEMS FOR SELECTIVELY FEEDING CHUNK POLYSILICON OR GRANULAR POLYSILICON IN A CRYSTAL GROWTH CHAMBER	TW	105126663	19-Aug-2016	201723241	1-Jul-2017		
SYSTEMS FOR SELECTIVELY FEEDING CHUNK POLYSILICON OR GRANULAR POLYSILICON IN A CRYSTAL GROWTH CHAMBER	US	15/753428					
SYSTEMS FOR SELECTIVELY FEEDING CHUNK POLYSILICON OR GRANULAR POLYSILICON IN A CRYSTAL GROWTH CHAMBER	KR	10-2018-7007845	20-Mar-2018				
SYSTEMS FOR SELECTIVELY FEEDING CHUNK POLYSILICON OR GRANULAR POLYSILICON IN A CRYSTAL GROWTH CHAMBER	JP	TBA	19-Feb-2018				
SYSTEMS FOR SELECTIVELY FEEDING CHUNK POLYSILICON OR GRANULAR POLYSILICON IN A CRYSTAL GROWTH CHAMBER	CN	TBA	20-Apr-2018				
SYSTEMS FOR SELECTIVELY FEEDING CHUNK POLYSILICON OR GRANULAR POLYSILICON IN A CRYSTAL GROWTH CHAMBER	EP	16766408.5	16-Mar-2018				
METHODS FOR PROCESSING SEMICONDUCTOR WAFERS HAVING A POLYCRYSTALLINE FINISH	TW	105131759	30-Sep-2016	201721750	16-Jun-2017		
METHODS FOR PROCESSING SEMICONDUCTOR WAFERS HAVING A POLYCRYSTALLINE FINISH	US	15/764272					